



**CY7C107B
CY7C1007B**

1M x 1 Static RAM

Features

- High speed
 - $t_{AA} = 12$ ns
- CMOS for optimum speed/power
- Automatic power-down when deselected
- TTL-compatible inputs and outputs

Functional Description

The CY7C107B and CY7C1007B are high-performance CMOS static RAMs organized as 1,048,576 words by 1 bit. Easy memory expansion is provided by an active LOW Chip Enable (CE) and three-state drivers. These devices have an automatic power-down feature that reduces power consumption by more than 65% when deselected.

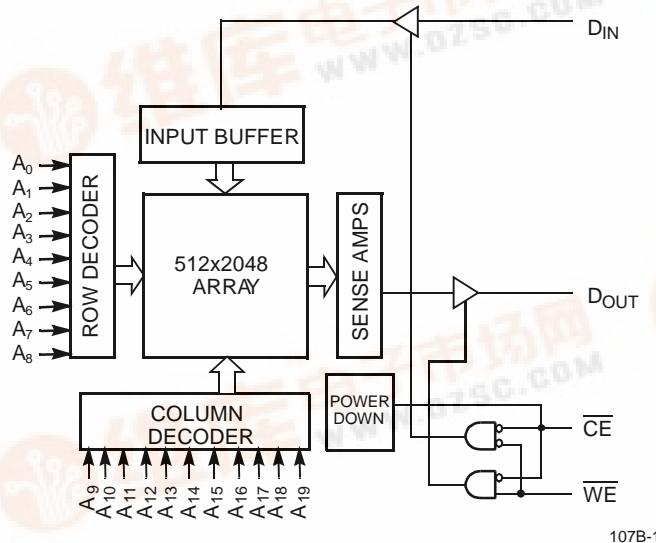
Writing to the devices is accomplished by taking Chip Enable (CE) and Write Enable (WE) inputs LOW. Data on the input pin (D_{IN}) is written into the memory location specified on the address pins (A_0 through A_{19}).

Reading from the devices is accomplished by taking Chip Enable (CE) LOW while Write Enable (WE) remains HIGH. Under these conditions, the contents of the memory location specified by the address pins will appear on the data output (D_{OUT}) pin.

The output pin (D_{OUT}) is placed in a high-impedance state when the device is deselected (CE HIGH) or during a write operation (CE and WE LOW).

The CY7C107B is available in a standard 400-mil-wide SOJ; the CY7C1007B is available in a standard 300-mil-wide SOJ.

Logic Block Diagram



Pin Configuration

SOJ Top View	
A ₁₀	1
A ₁₁	2
A ₁₂	3
A ₁₃	4
A ₁₄	5
A ₁₅	6
NC	7
A ₁₆	8
A ₁₇	9
A ₁₈	10
A ₁₉	11
D _{OUT}	12
WE	13
GND	14
V _{CC}	28
A ₉	27
A ₈	26
A ₇	25
A ₆	24
A ₅	23
A ₄	22
NC	21
A ₃	20
A ₂	19
A ₁	18
A ₀	17
D _{IN}	16
CE	15

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Selection Guide

	7C107B-12 7C1007B-12	7C107B-15 7C1007B-15	7C107B-20 7C1007B-20	7C107B-25 7C1007B-25	7C107B-35 7C1007B-35
Maximum Access Time (ns)	12	15	20	25	35
Maximum Operating Current (mA)	90	80	75	70	60
Maximum CMOS Standby Current SB2 (mA)	2	2	2	2	2



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Maximum Ratings

(Above which the useful life may be impaired. For user guidelines, not tested.)

Storage Temperature -65°C to +150°C

Ambient Temperature with Power Applied -55°C to +125°C

Supply Voltage on V_{CC} Relative to GND^[1] -0.5V to +7.0V

DC Voltage Applied to Outputs in High Z State^[1] -0.5V to V_{CC} + 0.5V

DC Input Voltage^[1] -0.5V to V_{CC} + 0.5V

Current into Outputs (LOW) 20 mA

Static Discharge Voltage >2001V
(per MIL-STD-883, Method 3015)

Latch-Up Current >200 mA

Operating Range

Range	Ambient Temperature ^[2]	V_{CC}
Commercial	0°C to +70°C	5V ± 10%
Industrial	-40°C to +85°C	5V ± 10%

Electrical Characteristics Over the Operating Range

Parameter	Description	Test Conditions	7C107B-12 7C1007B-12		7C107B-15 7C1007B-15		7C107B-20 7C1007B-20		Unit
			Min.	Max.	Min.	Max.	Min.	Max.	
V_{OH}	Output HIGH Voltage	$V_{CC} = \text{Min.}$, $I_{OH} = -4.0\text{ mA}$	2.4		2.4		2.4		V
V_{OL}	Output LOW Voltage	$V_{CC} = \text{Min.}$, $I_{OL} = 8.0\text{ mA}$		0.4		0.4		0.4	V
V_{IH}	Input HIGH Voltage		2.2	$V_{CC} + 0.3$	2.2	$V_{CC} + 0.3$	2.2	$V_{CC} + 0.3$	V
V_{IL}	Input LOW Voltage ^[1]		-0.3	0.8	-0.3	0.8	-0.3	0.8	V
I_{IX}	Input Load Current	$GND \leq V_I \leq V_{CC}$	-1	+1	-1	+1	-1	+1	μA
I_{OZ}	Output Leakage Current	$GND \leq V_I \leq V_{CC}$, Output Disabled	-5	+5	-5	+5	-5	+5	μA
I_{OS}	Output Short Circuit Current ^[3]	$V_{CC} = \text{Max.}$, $V_{OUT} = GND$		-300		-300		-300	mA
I_{CC}	V_{CC} Operating Supply Current	$V_{CC} = \text{Max.}$, $I_{OUT} = 0\text{ mA}$, $f = f_{MAX} = 1/\tau_{RC}$		90		80		75	mA
I_{SB1}	Automatic \overline{CE} Power-Down Current—TTL Inputs	Max. V_{CC} , $\overline{CE} \geq V_{IH}$, $V_{IN} \geq V_{IH}$ or $V_{IN} \leq V_{IL}$, $f = f_{MAX}$		20		20		20	mA
I_{SB2}	Automatic \overline{CE} Power-Down Current—CMOS Inputs	Max. V_{CC} , $\overline{CE} \geq V_{CC} - 0.3V$, $V_{IN} \geq V_{CC} - 0.3V$ or $V_{IN} \leq 0.3V$, $f = 0$		2		2		2	mA

Notes:

1. V_{IL} (min.) = -2.0V for pulse durations of less than 20 ns.
2. T_A is the "Instant On" case temperature.
3. Not more than 1 output should be shorted at one time. Duration of the short circuit should not exceed 30 seconds.



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Electrical Characteristics Over the Operating Range (continued)

Parameter	Description	Test Conditions	7C107B-25 7C1007B-25		7C107B-35 7C1007B-35		Unit
			Min.	Max.	Min.	Max.	
V_{OH}	Output HIGH Voltage	$V_{CC} = \text{Min.}, I_{OH} = -4.0 \text{ mA}$	2.4		2.4		V
V_{OL}	Output LOW Voltage	$V_{CC} = \text{Min.}, I_{OL} = 8.0 \text{ mA}$		0.4		0.4	V
V_{IH}	Input HIGH Voltage		2.2	$V_{CC} + 0.3$	2.2	$V_{CC} + 0.3$	V
V_{IL}	Input LOW Voltage ^[1]		-0.3	0.8	-0.3	0.8	V
I_{IX}	Input Load Current	$GND \leq V_I \leq V_{CC}$	-1	+1	-1	+1	μA
I_{OZ}	Output Leakage Current	$GND \leq V_I \leq V_{CC}$, Output Disabled	-5	+5	-5	+5	μA
I_{OS}	Output Short Circuit Current ^[3]	$V_{CC} = \text{Max.}, V_{OUT} = GND$		-300		-300	mA
I_{CC}	V_{CC} Operating Supply Current	$V_{CC} = \text{Max.},$ $I_{OUT} = 0 \text{ mA},$ $f = f_{MAX} = 1/t_{RC}$		70		60	mA
I_{SB1}	Automatic \overline{CE} Power-Down Current—TTL Inputs	Max. $V_{CC}, \overline{CE} \geq V_{IH},$ $V_{IN} \geq V_{IH}$ or $V_{IN} \leq V_{IL},$ $f = f_{MAX}$		20		20	mA
I_{SB2}	Automatic \overline{CE} Power-Down Current—CMOS Inputs	Max. $V_{CC},$ $\overline{CE} \geq V_{CC} - 0.3V,$ $V_{IN} \geq V_{CC} - 0.3V$ or $V_{IN} \leq 0.3V, f = 0$		2		2	mA

Capacitance^[4]

Parameter	Description	Test Conditions	Max.	Unit
C_{IN} : Addresses	Input Capacitance	$T_A = 25^\circ C, f = 1 \text{ MHz},$ $V_{CC} = 5.0V$	7	pF
C_{IN} : Controls			10	pF
C_{OUT}	Output Capacitance		10	pF

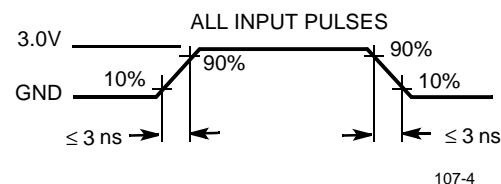
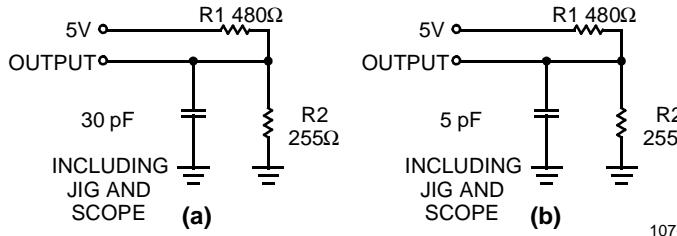
Note:

4. Tested initially and after any design or process changes that may affect these parameters.



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AC Test Loads and Waveforms



Equivalent to: THÉVENIN EQUIVALENT

$$\text{OUTPUT} \xrightarrow{167\Omega} 1.73\text{V}$$

Switching Characteristics^[5] Over the Operating Range

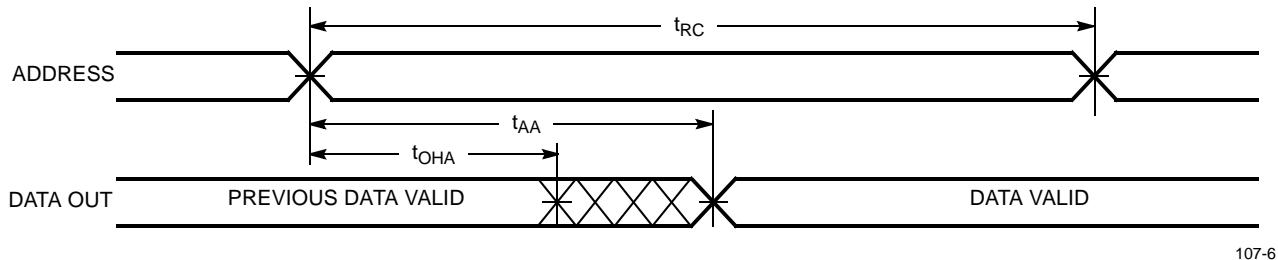
Parameter	Description	7C107B-12 7C1007B-12		7C107B-15 7C1007B-15		7C107B-20 7C1007B-20		7C107B-25 7C1007B-25		7C107B-35 7C1007B-35		Unit
		Min.	Max.									
READ CYCLE												
t _{RC}	Read Cycle Time	12		15		20		25		35		ns
t _{AA}	Address to Data Valid		12		15		20		25		35	ns
t _{HOA}	Data Hold from Address Change	3		3		3		3		3		ns
t _{ACE}	CE LOW to Data Valid		12		15		20		25		35	ns
t _{LZCE}	CE LOW to Low Z ^[6]	3		3		3		3		3		ns
t _{HZCE}	CE HIGH to High Z ^[6, 7]		6		7		8		10		10	ns
t _{PU}	CE LOW to Power-Up	0		0		0		0		0		ns
t _{PD}	CE HIGH to Power-Down		12		15		20		25		35	ns
WRITE CYCLE^[8]												
t _{WC}	Write Cycle Time	12		15		20		25		35		ns
t _{SCE}	CE LOW to Write End	10		12		15		20		25		ns
t _{AW}	Address Set-Up to Write End	10		12		15		20		25		ns
t _{HA}	Address Hold from Write End	0		0		0		0		0		ns
t _{SA}	Address Set-Up to Write Start	0		0		0		0		0		ns
t _{PWE}	WE Pulse Width	10		12		15		20		25		ns
t _{SD}	Data Set-Up to Write End	7		8		10		15		20		ns
t _{HD}	Data Hold from Write End	0		0		0		0		0		ns
t _{LZWE}	WE HIGH to Low Z ^[6]	3		3		3		3		3		ns
t _{HZWE}	WE LOW to High Z ^[6, 7]		6		7		8		10		10	ns

Notes:

5. Test conditions assume signal transition time of 3 ns or less, timing reference levels of 1.5V, input pulse levels of 0 to 3.0V, and output loading of the specified I_{OL}/I_{OH} and 30-pF load capacitance.
6. At any given temperature and voltage condition, t_{HZCE} is less than t_{LZCE} and t_{HZWE} is less than t_{LZWE} for any given device.
7. t_{HZCE} and t_{HZWE} are specified with a load capacitance of 5 pF as in part (b) of AC Test Loads. Transition is measured ±500 mV from steady-state voltage.
8. The internal write time of the memory is defined by the overlap of CE LOW and WE LOW. CE and WE must be LOW to initiate a write, and the transition of any of these signals can terminate the write. The input data set-up and hold timing should be referenced to the leading edge of the signal that terminates the write.

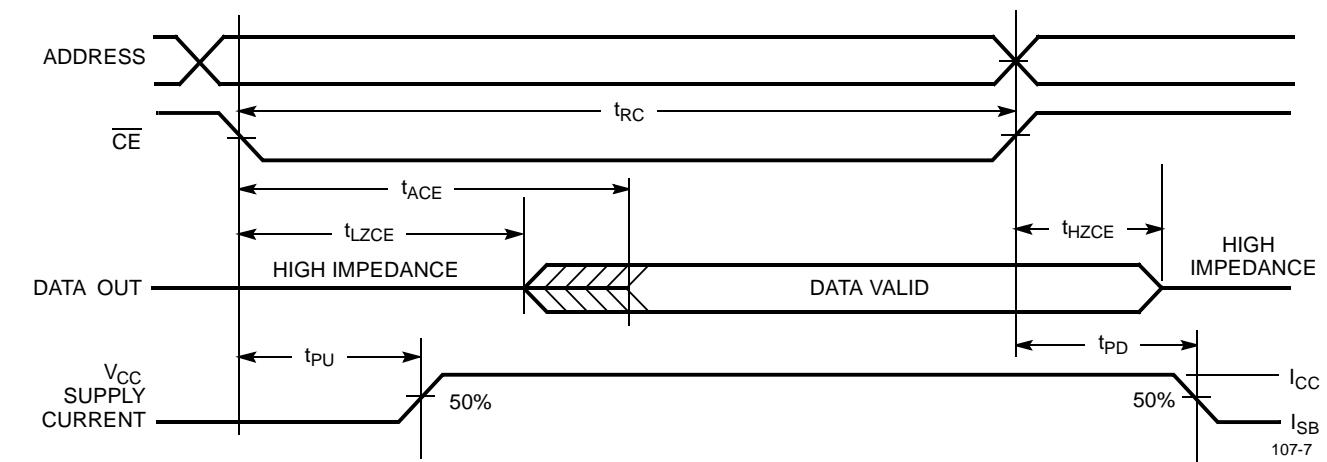
Switching Waveforms

Read Cycle No. 1^[10, 11]

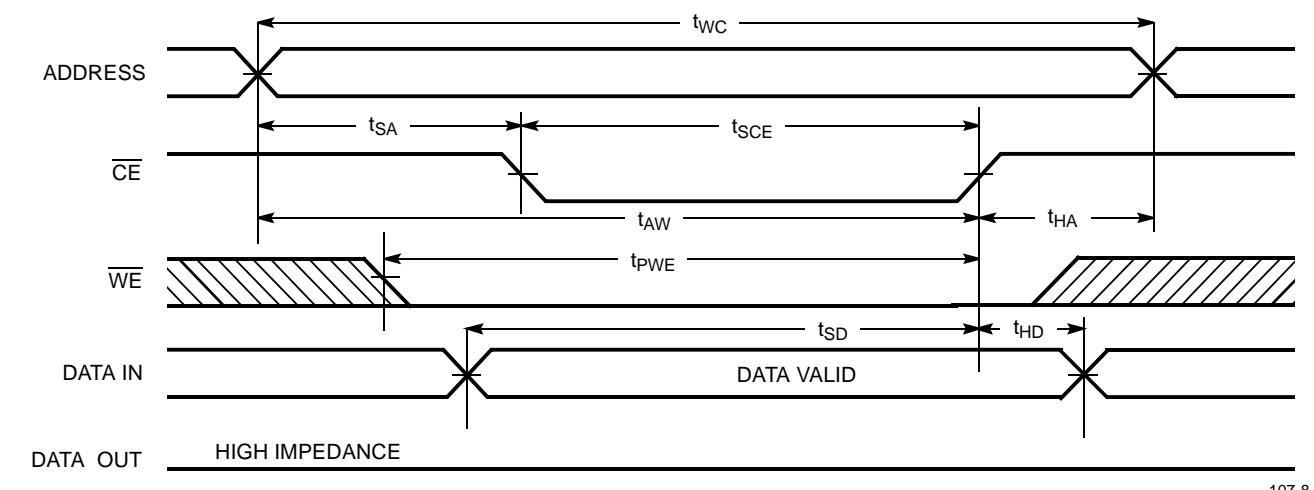


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Read Cycle No. 2^[11, 12]



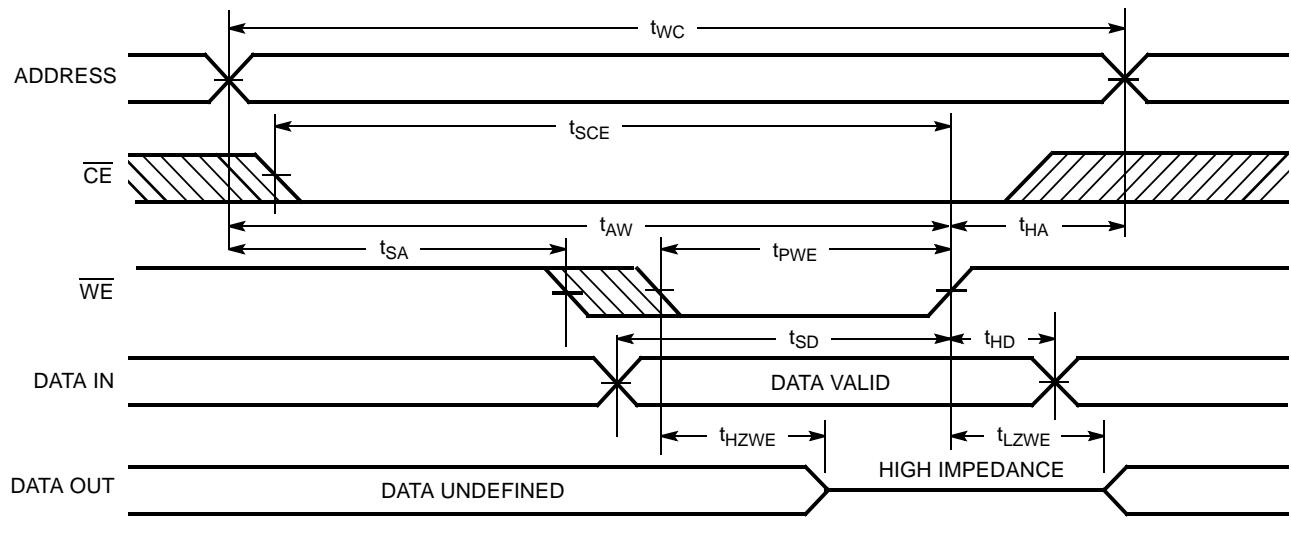
Write Cycle No. 1 (CE Controlled)^[13]



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Notes:

9. No input may exceed V_{CC} + 0.5V.
10. Device is continuously selected, $\overline{CE} = V_{IL}$.
11. WE is HIGH for read cycle.
12. Address valid prior to or coincident with \overline{CE} transition LOW.

Switching Waveforms (continued)
Write Cycle No. 2 (WE Controlled)^[13]


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Note:

13. If \overline{CE} goes HIGH simultaneously with \overline{WE} going HIGH, the output remains in a high-impedance state.



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Truth Table

CE	WE	D_{OUT}	Mode	Power
H	X	High Z	Power-Down	Standby (I _{SB})
L	H	Data Out	Read	Active (I _{CC})
L	L	High Z	Write	Active (I _{CC})

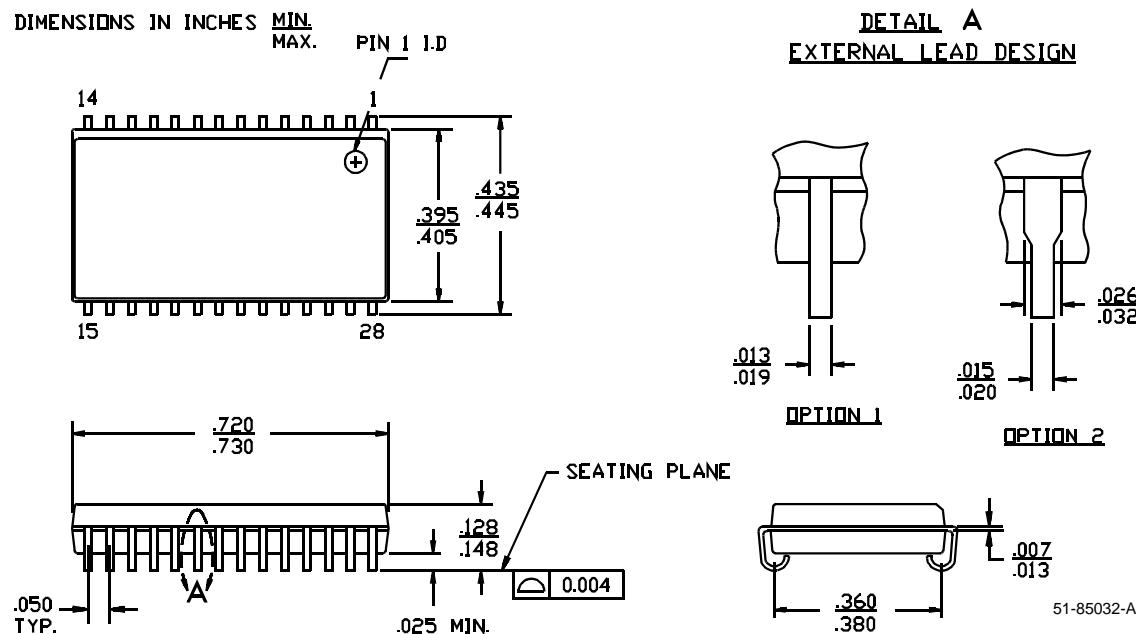
Ordering Information

Speed (ns)	Ordering Code	Package Name	Package Type	Operating Range
12	CY7C107B-12VC	V28	28-Lead (400-Mil) Molded SOJ	Commercial
	CY7C1007B-12VC	V28	28-Lead (300-Mil) Molded SOJ	Commercial
15	CY7C107B-15VC	V28	28-Lead (400-Mil) Molded SOJ	Commercial
	CY7C1007B-15VC	V28	28-Lead (300-Mil) Molded SOJ	Commercial
15	CY7C107B-15VI	V28	28-Lead (400-Mil) Molded SOJ	Industrial
	CY7C1007B-15VI	V28	28-Lead (300-Mil) Molded SOJ	Industrial
20	CY7C107B-20VC	V28	28-Lead (400-Mil) Molded SOJ	Commercial
	CY7C1007B-20VC	V28	28-Lead (300-Mil) Molded SOJ	Commercial
25	CY7C107B-25VC	V28	28-Lead (400-Mil) Molded SOJ	Commercial
	CY7C1007B-25VC	V28	28-Lead (300-Mil) Molded SOJ	Commercial

Contact factory for "L" version availability.

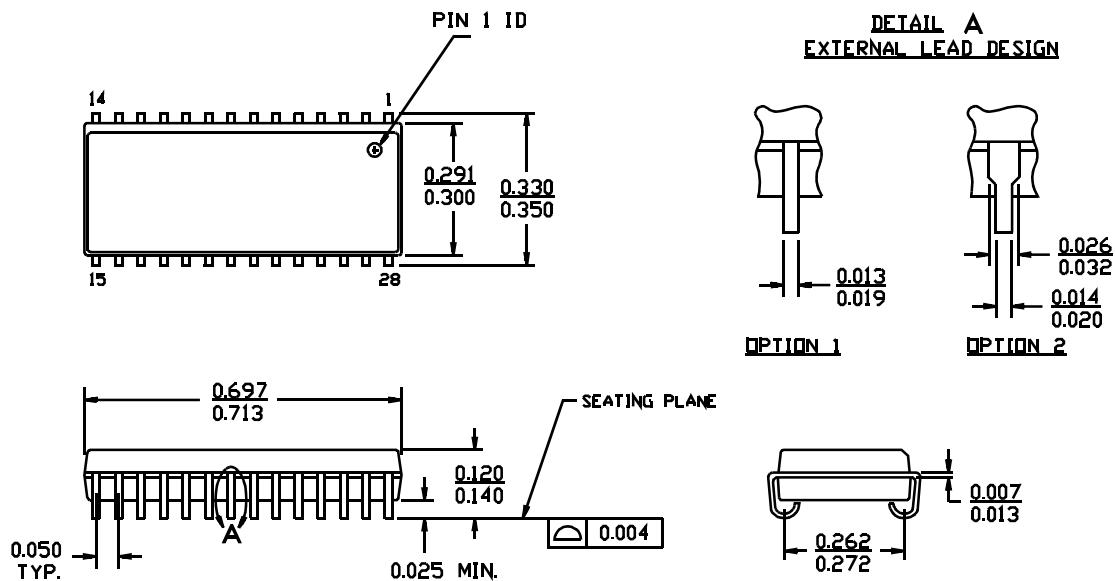
Package Diagrams

28-Lead (400-Mil) Molded SOJ V28



28-Lead (300-Mil) Molded SOJ V21

DIMENSIONS IN INCHES MIN. MAX.





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**Document Title: CY7C107B/CY7C1007B 1M x 1 Static RAM
Document Number: 38-05030**

REV.	ECN NO.	Issue Date	Orig. of Change	Description of Change
**	109950	12/02/01	SZV	Change from Spec number: 38-01116 to 38-05030